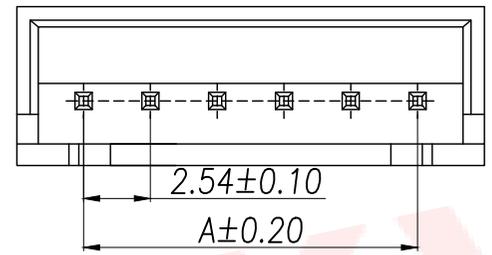
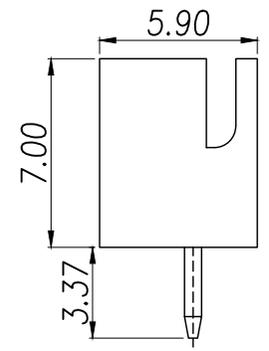
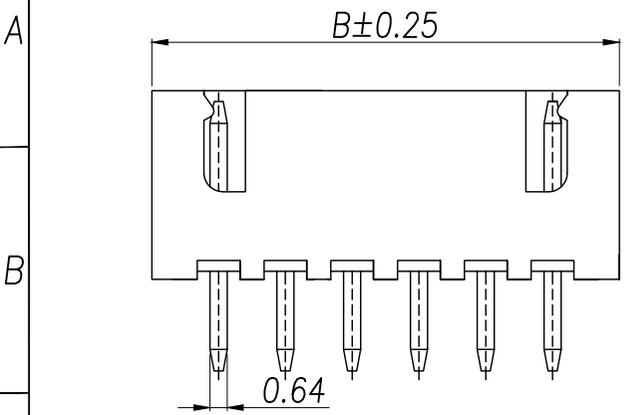


REV.	Q'TY	ECN. NO.	APR.	DATE

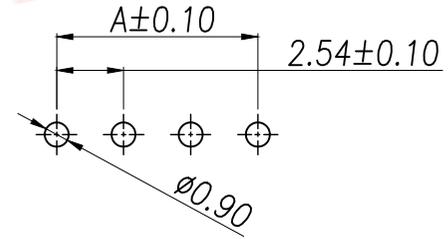
Part No	Pin	A	B
XY-B2B-XH-A	2	2.50	7.50
XY-B3B-XH-A	3	5.00	10.00
XY-B4B-XH-A	4	7.50	12.50
XY-B5B-XH-A	5	10.00	15.00
XY-B6B-XH-A	6	12.50	17.50
XY-B7B-XH-A	7	15.00	20.00
XY-B8B-XH-A	8	17.50	22.50
XY-B9B-XH-A	9	20.00	25.00
XY-B10B-XH-A	10	22.50	27.50
XY-B11B-XH-A	11	25.00	30.00
XY-B12B-XH-A	12	27.50	32.50
XY-B13B-XH-A	13	30.00	35.00
XY-B14B-XH-A	14	32.50	37.50
XY-B15B-XH-A	15	35.00	40.00
XY-B16B-XH-A	16	37.50	42.50
XY-B17B-XH-A	17	40.00	45.00
XY-B18B-XH-A	18	42.50	47.50
XY-B19B-XH-A	19	45.00	50.00
XY-B20B-XH-A	20	47.50	52.50



技术要求:

1. 塑件材料: PA66(UL-94V-0)
2. 接触件: 黄铜镀锡
3. 接触电阻: $\leq 10m\Omega$
4. 绝缘电阻: $\geq 100M\Omega$
5. 额定电压: 250V AC DC
6. 额定电流: 2.0A AC DC
7. 耐压: 能承受 1000V AC/Minute
8. 工作温度: $-25^{\circ}\sim+85^{\circ}$
9. 可焊性试验: 浸锡面积 > 95% 温度 235 , 时间 2 ± 0.5 秒
10. 铅和锡等六大有害物质含量要符合环保要求。

序号	名称	材料	数量	备注
2	端子 Contact	黄铜	N*1	电镀(锡): 整个表面镀底镍 30u"MIN, 再镀锡 80u"MIN
1	基座 Wafer	PA66(UL94V-0)	1	白色



SUGGESTED PCB LAYOUT
(COMPONENT SIDE)

DIMENSION IN mm		厦门市辛译精密电子有限公司 Xiamen XinYi Xyecomm Electronics Co.,Ltd			
TOLERANCE UNLESS OTHERWISE SPECIFIED		APR.	TITLE: WAFER XH2.54MM 1#		
.X±0.2	X.*± 2'	Alex	CHK.	Jack	
.XX±0.10	.X'±		DWG NO. XY-BNB-XH-A		
.XXX±0.05	.XX'±	DRA.	PROJ.	CUSTOMER DRAWING	
		Can	SIZE A4	SCALE 1:1	SHEET 1/1
				REV.	A